g		GE Energy	,	Function	al Testing Spe	ecification		
Parts & Repair Services Louisville, KY				LOU-GED-DS200TBQF				
	Zodrovinoj K		ure for a Transit	ion Module				
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#### 1. SCOPE

**1.1** This is a functional testing procedure for a DS200TBQFG1B.

## 2. STANDARDS OF QUALITY

**2.1** Refer to the current revision of the IPC-A-610 standard for workmanship standards.

#### 3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
  - 3.1.1 DS200TBQFG1B SH 4AA-4DA

## 4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
  - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.
- **4.2** Equipment Inspection
  - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
    - 4.2.1.1 Wires broken, cracked, or loosely connected
    - 4.2.1.2 Terminal strips / connectors broken or cracked
    - 4.2.1.3 Components visually damaged
    - 4.2.1.4 Capacitors bloated or leaking
    - 4.2.1.5 Solder joints damaged or cold
    - 4.2.1.6 Circuit board burned or de-laminated
    - 4.2.1.7 Printed wire runs / Traces burned or damaged

#### 5. EQUIPMENT REQUIRED

**5.1** The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		DC Power Supply

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# 6. TESTING PROCESS

- 6.1 Setup
  - **6.1.1** Set power supply to ~26VDC
  - **6.1.2** Connect (-) from power supply to C1 (-)
  - **6.1.3** Connect (+) from PS to C1 (+)
  - **6.1.4** Connect common from DMM to C1 (-)
- 6.2 Testing Procedure
  - 6.2.1 Apply power to card
  - **6.2.2** Check for +24VDC +/- .2VDC at the following points. TB37, TB38, TB43, TB44, TB49, TB50, TB55, TB56, TB61, TB62, TB67, TB68, TB73, TB74, TB79
  - 6.2.3 Component check remainder of card
- 6.3 \*\*\*TEST COMPLETE \*\*\*
- 7. NOTES
  - 7.1 None at this time
- 8. ATTACHMENTS
  - 8.1 None at this time